

DSC9F01

Silicon NPN epitaxial planar type

For high-frequency amplification
DSC5F01 in SSMini3 type package

■ Features

- High forward current transfer ratio h_{FE} with excellent linearity
- High transition frequency f_T
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

■ Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter | Symbol | Rating | Unit |
|---------------------------------------|-----------|-------------|------------------|
| Collector-base voltage (Emitter open) | V_{CBO} | 15 | V |
| Collector-emitter voltage (Base open) | V_{CEO} | 10 | V |
| Emitter-base voltage (Collector open) | V_{EBO} | 3 | V |
| Collector current | I_C | 50 | mA |
| Collector power dissipation | P_C | 125 | mW |
| Junction temperature | T_j | 150 | $^\circ\text{C}$ |
| Storage temperature | T_{stg} | -55 to +150 | $^\circ\text{C}$ |

■ Package

- Code
SSMini3-F3-B
- Pin Name
 1. Base
 2. Emitter
 3. Collector

■ Marking Symbol: C7

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

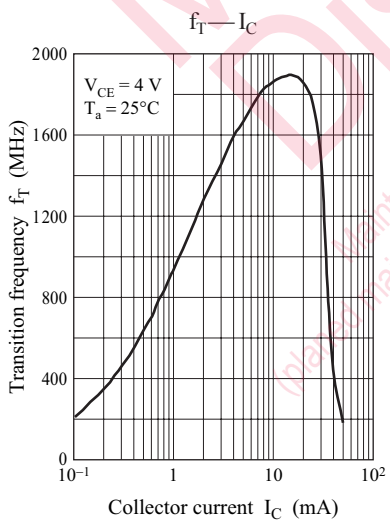
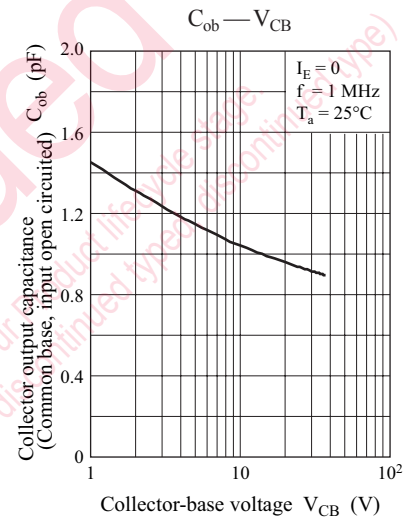
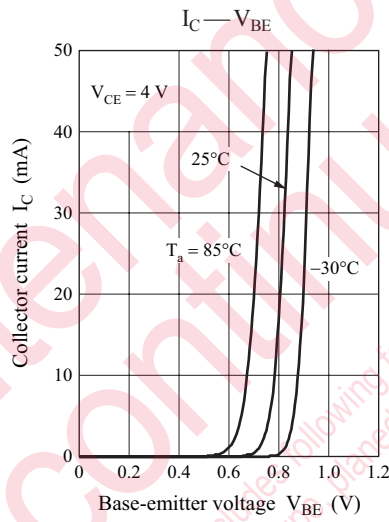
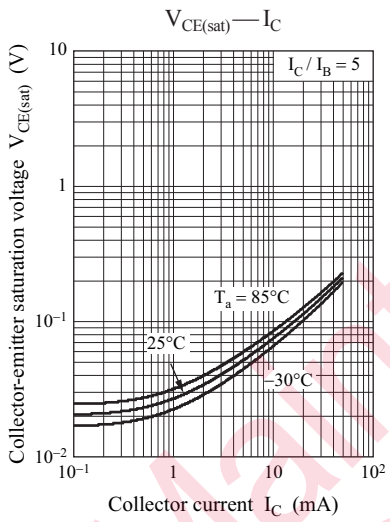
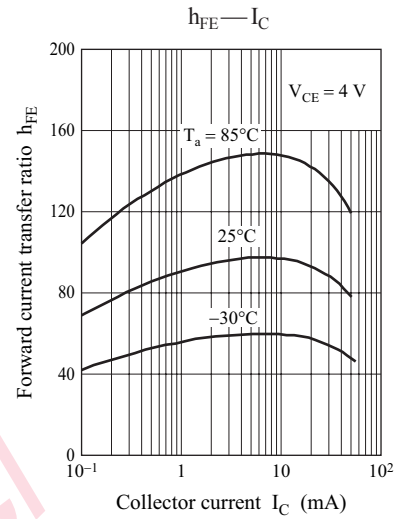
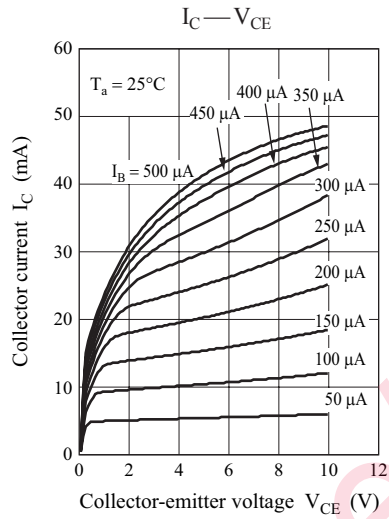
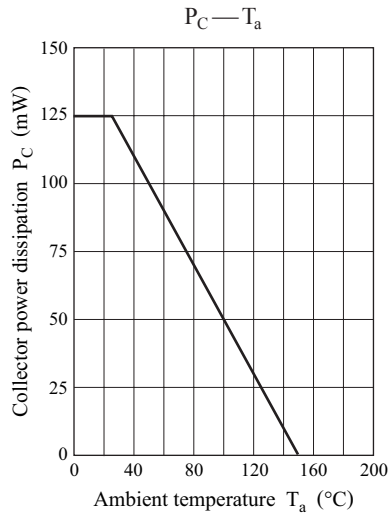
| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|---|---------------------|--|-----|-----|-----|---------------|
| Collector-emitter voltage (Base open) | V_{CEO} | $I_C = 2 \text{ mA}, I_B = 0$ | 10 | | | V |
| Emitter-base voltage (Collector open) | V_{EBO} | $I_E = 10 \mu\text{A}, I_C = 0$ | 3 | | | V |
| Collector-base cutoff current (Emitter open) | I_{CBO} | $V_{CB} = 10 \text{ V}, I_E = 0$ | | | 1 | μA |
| Forward current transfer ratio * | h_{FE} | $V_{CE} = 4 \text{ V}, I_C = 5 \text{ mA}$ | 75 | | 220 | — |
| Collector-emitter saturation voltage | $V_{CE(sat)}$ | $I_C = 20 \text{ mA}, I_B = 4 \text{ mA}$ | | | 0.5 | V |
| Transition frequency | f_T | $V_{CE} = 4 \text{ V}, I_C = 5 \text{ mA}$ | | 1.9 | | GHz |
| Collector output capacitance (Common base, input open circuited) | C_{ob} | $V_{CB} = 4 \text{ V}, I_E = 0, f = 1 \text{ MHz}$ | | 1.2 | | pF |
| Collector-base parameter | $r_{bb}' \cdot C_C$ | $V_{CE} = 4 \text{ V}, I_C = 5 \text{ mA}, f = 31.9 \text{ MHz}$ | | 12 | | ps |
| Reverse transfer capacitance (Common base) | C_{rb} | $V_{CE} = 4 \text{ V}, I_C = 0, f = 1 \text{ MHz}$ | | 0.6 | | pF |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Rank classification

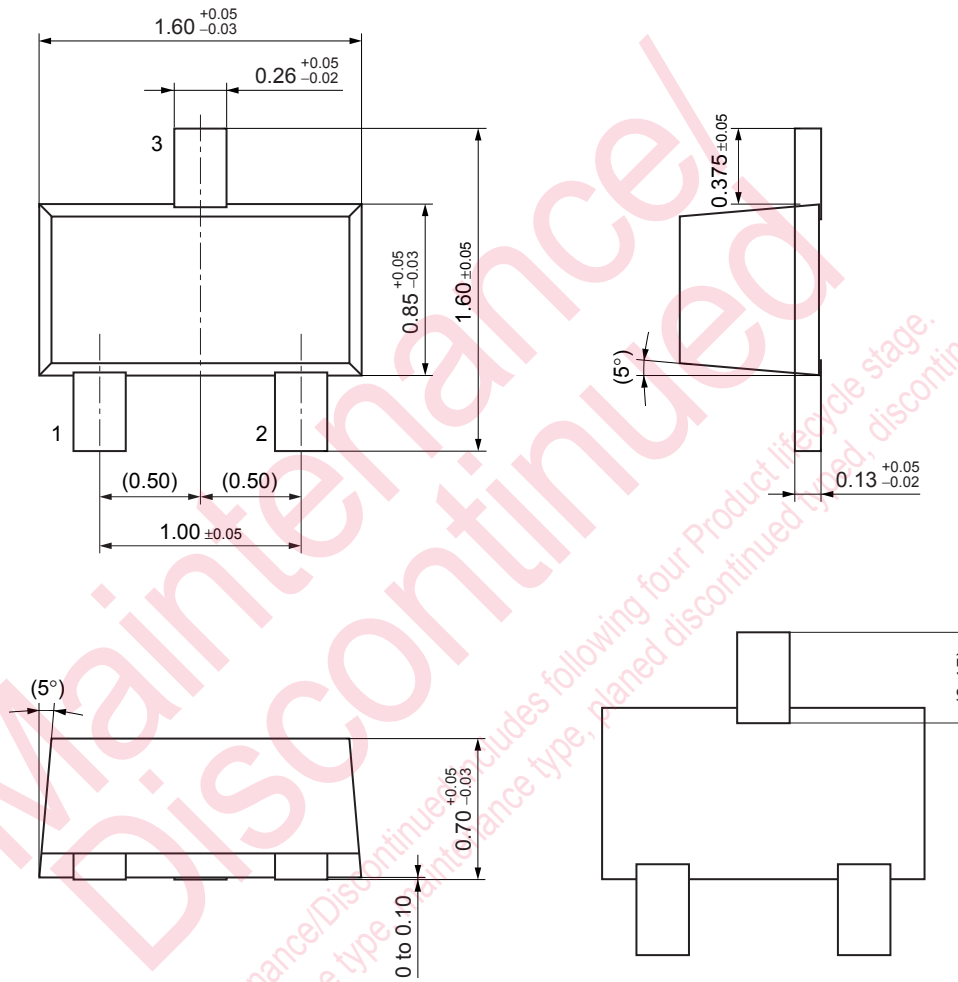
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|----------------|-----------|------------|-----------|
| Code | P | Q | 0 |
| Rank | P | Q | No-rank |
| h_{FE} | 75 to 130 | 110 to 220 | 75 to 220 |
| Marking Symbol | C7P | C7Q | C7 |

Product of no-rank is not classified and have no marking symbol for rank.



SSMini3-F3-B

Unit: mm



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